Product Change Notice

PCN Number: 12-0522-04
Issue Date: 05-06-2013

Exar Corporation
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PRODUCTS AFFECTED:	SP508CF-L, SP508EF-L

CHANGE CATEGORY:

☐ Material	☒ Process	☐ Package
☐ Design	☒ Datasheet	☐ Packing/Shipping
☐ Other (specify)		

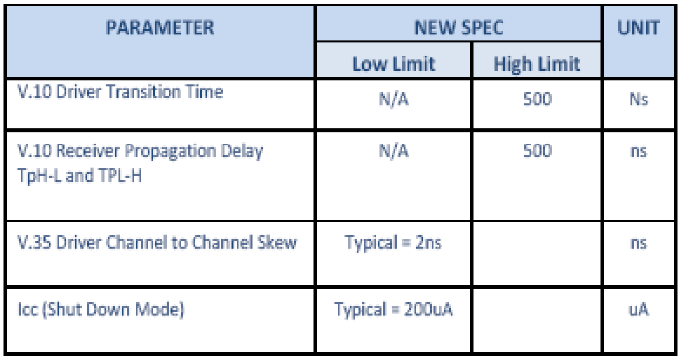
DESCRIPTION OF CHANGE:
Change in wafer fabrication foundry and part numbers.
Qualification of an alternate qualified wafer foundry, Silan, in addition to the current wafer foundry, Episil Technologies.

FROM:	**TO:**
Part Numbers: • SP508CF-L • SP508EF-L	Part Numbers: • SP508ECF-L • SP508EEF-L

Datasheet limits for the following parameters are being changed from:

PARAMETER	OLD SPEC		UNIT
	Low Limit	High Limit	
V.10 Driver Transition Time	N/A	200	Ns
V.10 Receiver Propagation Delay TpH-L and TPL-H	N/A	60	ns
V.35 Driver Channel to Channel Skew	Typical = 5nS		ns
Icc (Shut Down Mode)	Typical = 1uA		uA

Datasheet limits for the following parameters are being changed to:



PARAMETER	NEW SPEC		UNIT
	Low Limit	High Limit	
V.10 Driver Transition Time	N/A	500	Ns
V.10 Receiver Propagation Delay TpH-L and TPL-H	N/A	500	ns
V.35 Driver Channel to Channel Skew	Typical = 2ns		ns
Icc (Shut Down Mode)	Typical = 200uA		uA

IMPACT OF CHANGE:
None expected for known customer applications.

TARGET IMPLEMENTATION DATE: 29-APR-2013

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data